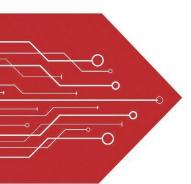
## MSKSEMI















**ESD** 

TVS

**TSS** 

MOV

**GDT** 

**PLED** 

# Broduct data sheet

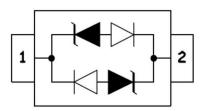






SOD-323

## **PIN CONFIGURATION**



#### **FEATURES**

→ Transient protection for high-speed datalines IEC 61000-4-2 (ESD) ±30kV (Contact) ±30kV (Air)

IEC 61000-4-4 (EFT) 40A (5/50 ns)

- ♦ Protects one I/O line (bidirectional)
- ♦ Working voltages : 24V
- ♦ Low clamping voltage
- ♦ Low leakage current
- ♦ Response time is < 1 ns</p>

#### **MACHANICAL DATA**

- ♦ SOD-323 package
- ♦ Packaging: Tape and Reel
- ♦ High temperature soldering guaranteed: 260°C/10s
- ♦ Reel size: 7 inch
- ♦ MSL1

#### **APPLICATIONS**

- ♦ Cell Phone Handsets and Accessories
- ♦ Microprocessor based equipment
- ♦ Personal Digital Assistants (PDA's)
- ♦ Notebooks, Desktops, and Servers
- ♦ Portable Instrumentation
- ♦ Peripherals



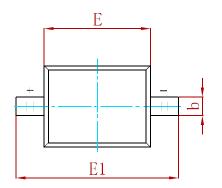
## **Bi-directional Ultra Low Capacitance TVS Array**

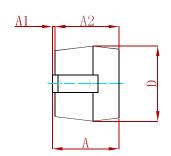
ABSOLUTE MAXIMUM RATING					
Symbol	Parameter	Value	Units		
V <sub>ESD</sub>	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±30 ±30	kV		
P <sub>PP</sub>	Peak Pulse Power (8/20µs)	350	W		
Т <sub>ОРТ</sub>	Operating Temperature	-55/+150	°C		
T <sub>STG</sub>	Storage Temperature	-55/+150	°C		
TL	Lead Soldering Temperature	260	°C		

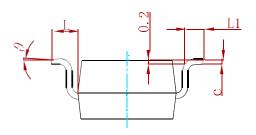
ELECTRICAL CHARACTERISTICS (Tamb=25°C)										
		$V_{RWM}$	V <sub>B</sub> @1mA	Vc@1A	V <sub>C</sub> @	)lpp	V <sub>C</sub> @	plpp	I <sub>R</sub>	Ст
		(V)	(V)	(V)	(V)		(V)		(µA)	(pF)
P/N	MARKING	Max	Min	Max	Max	lpp (A)	Max	lpp (A)	Max	Тур.
PDYL240B-MS	HC	24.0	26.7	43.0	45.0	3	56.0	6	1	0.8



## **PACKAGE MECHANICAL DATA**

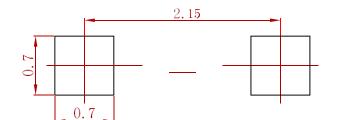






Cyrmala a l	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.000		0.039	
A 1	0.000	0.100	0.000	0.004	
A2	0.800	0.900	0.031	0.035	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	1.200	1.400	0.047	0.055	
E	1.600	1.800	0.063	0.071	
E1	2.550	2.750	0.100	0.108	
L,	0.475	REF.	0.019	REF.	
L1	0.250	0.400	0.010	0.016	
θ	0°	8°	0°	8°	

## **Suggested Pad Layout**



## Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
PDYL240B-MS	SOD-323	3000



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